

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free):   XC9264xxxxMR-G  
Typical Mass:           16     mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.666	Silicon	41600	7440-21-3
	-	Arsenic	<1	7440-38-2
Leadframe	3.678	Copper	229900	7440-50-8
	0.009	Tin	600	7440-31-5
	0.009	Chromium	500	7440-47-3
	0.007	Zinc	400	7440-66-6
	0.234	Silver	14600	7440-22-4
Die attach	0.032	Epoxy resin	2000	—
	0.023	Silica (crystal)	1500	14808-60-7
Bonding wire	0.102	Gold	6400	7440-57-5
Resin	9.499	Silica	593700	60676-86-0
	1.173	Epoxy resin	73300	—
	0.335	Phenol resin	21000	—
Plating	0.232	Tin	14500	7440-31-5

\* The component composition is based on the information provided by raw material vendor.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."